

Abstract

5 An integrated circuit comprising a die having a surface. The die may comprise first and second areas. The first area may comprise first circuit cells. The first circuit cells may be configurable by user defined interconnections from above the surface. The second area may comprise a plurality of sub-circuit cells. The sub-circuit cells may form a module having a predefined functionality. The sub-circuit cells may include at least one second circuit cell. The second circuit cell may be configured such that when the predefined
10 functionality of the module is not used, the second circuit cell is configurable by user defined interconnections from above the surface.